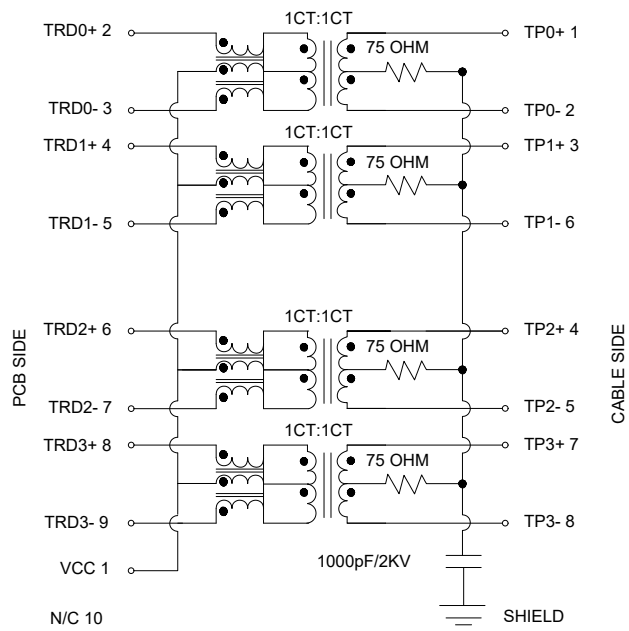


RECOMMENDED PCB LAYOUT



CIRCUIT SCHEMATIC



NOTES:  
 HOUSING : NYLON66 GLASS FILLED UL94V-0 BLACK  
 SHIELD : C2680H NICKEL PLATING 20u" MIN.  
 RJ TERMINAL : NYLON66 UL94V-0 BLACK C5210EH NICKEL PLATING 40U"~60U" FOR ALL TIN 100% AND GOLD PLATING  
 INPUT TERMINAL : NYLON66 GLASS FILLED UL94V-0 BLACK SUS430 NICKEL PLATING 40U"~60U" FOR ALL AND TIN 100%  
 OPERATION TEMPERATURE : 0 ~ +70°C

PARAMETER	SPECIFICATIONS	
URNS RATIO	1.00±2%	
POLARITY	PER SCHEMATIC	
PRIMARY INDUCTANCE	120uH Min. @100KHz, 100mV	
INSERTION LOSS	1-65MHz	-0.8dB Max.
	65-125MHz	-1.0dB Max.
	125-400MHz	-2.5dB Max.
RETURN LOSS	400-500MHz	-3.5dB Max.
	1-40MHz	-18dB Min.
	40-400MHz	-18+10*LOG <sub>10</sub> (f/40) dB Min.
CROSS TALK ADJACENT CHANNELS (SDD21-ADJ.)	300-500MHz	-8+30*LOG <sub>10</sub> (f/400) dB Min.
	1-100MHz	-30dB Min.
COMMON MODE REJECTION RATIO (SCC21)	100-500MHz	-20dB Min.
	1-100MHz	-30dB Min.
	100-300MHz	-22dB Min.
COMM. TO DIFF REJECTION RATIO (SDC12)	300-500MHz	-17dB Min.
	1-100MHz	-32dB Min.
	100-300MHz	-27dB Min.
ISOLATION	2250V DC FOR 60s	

		UNIT	mm
		REVISION	P1
PRODUCT		TOLERANCES	
RJ45 1x2 ICM 10G BASE-T		.0 ± 0.38	
DWG NO.	PART NO.	.00 ± 0.20	
EZ111S-210ND21-01		.000 ± 0.10	
PROJECTION	SCALE	0° ± 2.0°	
		.0° ± 1.0°	
	SHEET	1 OF 1	